# Architecture of Semiconductor Electronics Manufacturing FABs in India: Functionality, Aesthetics and Human Experience

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***Abstract*—Semiconductor electronics are the backbone of nearly every technology we use in our modern way of life, powering everything from smartphones and computers to household appliances, vehicles, and advanced fields like telecommunications, robotics, and artificial intelligence (AI). As India strives to establish a self-reliant semiconductor electronics ecosystem, the architectural design of their manufacturing facilities (FABs) becomes critically important. These facilities must not only meet stringent functional and operational standards but also may embody their national importance through architectural expression.**

**This paper provides a holistic approach to designing semiconductor electronics manufacturing FABs, focusing on both technical and human-centered aspects. It covers site selection, spatial planning, structural systems, cleanroom specifications, and utility management, while also considering user well-being. This includes considering worker routines, implementing safety measures, and exploring design ideas that foster health and satisfaction. It emphasizes how aesthetics can enhance these facilities, boosting worker morale and positively shaping industry perception. Achieving a blend of functionality and beauty is key to attracting investment, talent, and public interest to the industry. By exploring the intersection of functionality, aesthetics, and human experience, this paper contributes to both designing the architecture of FABs and the broader discourse on industrial architecture.**

***Keywords— Semiconductor Electronics, FAB, Industrial Architecture, Architectural Design, Manufacturing Facilities***

## 1. Introduction

Semiconductor electronics are the foundation of nearly every technology we use today, from the smartphones in our hands and the computers at our desks, to household appliances like LED lights and television, and even transportation vehicles such as cars and planes. In cutting-edge technologies like telecommunications, robotics and artificial intelligence (AI), semiconductor electronics are indispensable. These tiny components power virtually every aspect of our modern way of life.

Recognizing the critical role of these components, India is striving to establish a robust semiconductor manufacturing industry to reduce reliance on imports and foster technological self-reliance. Semiconductor devices are crucial to a variety of sectors, including industrial, commercial, defense, and space applications. Developing an integrated semiconductor ecosystem will not only bolster national security but also position India as a leader in electronics, aligning with its ambitions for innovation and global influence.

The growth trajectory of India's semiconductor market reflects these strategic aims, with semiconductor consumption projected to expand from \$22 billion in 2019 to \$64 billion by 2026 at a 16% CAGR (Compound Annual Growth Rate). By 2030, this figure is expected to reach \$110 billion, making India a significant contributor to global semiconductor demand at approximately 10%. This rising demand underscores the urgent need for semiconductor manufacturing infrastructure, with FABs becoming essential assets in achieving India's vision for technological advancement. [2]

The architecture of semiconductor manufacturing facilities, or FABs, is inherently complex, shaped by the stringent technical and environmental requirements of chip production. Cleanrooms are central to these facilities, demanding precise control of temperature, humidity, and air purity to prevent contamination. Structural designs must support heavy, specialized machinery, and extensive utility networks are required for water, power, and chemical management.

Architects play a vital role in bridging the technical rigor of FAB design with human-centered and aesthetic considerations. Working closely with engineers, they translate exacting manufacturing requirements into spaces that are functional, efficient, and attuned to the well-being of employees. Beyond operational efficiency, architects focus on creating aesthetically appealing environments, incorporating elements like natural lighting, open spaces, and ergonomic designs that foster a positive working atmosphere. Through thoughtful design, architects make semiconductor facilities not only functional but also iconic, having the potential to embody India's aspirations in the global technology landscape and setting a standard for industrial architecture that combines functionality with beauty.

## 1.1. About Semiconductor Electronics

*1.1.1.* ***What are Semiconductors?*** Semiconductors are materials with electrical conductivity between that of conductors and insulators. This property allows them to regulate electrical current with high precision, which is fundamental to the operation of electronic devices. The most widely used semiconductor material is Silicon, but others, like Gallium Arsenide and Germanium, are also employed for specialized applications [3]. These materials enable precise control of current flow, making them ideal for building electronic components that can compute, switch, amplify, or manage signals [4].


Fig. 1 A piece of purified Silicon


Fig. 2 Purified Silicon Ingots

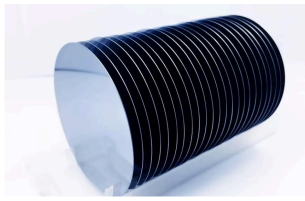


Fig. 3 Polished Silicon Wafers

*1.1.2.* ***Semiconductor Electronics:*** Semiconductor electronics are composed of intricate and miniaturized circuits made from semiconductor materials. These devices include transistors, diodes, integrated circuits (ICs), and microchips, all of which are extremely small and delicate, allowing for complex processing within a compact space [5]. The scale of these components is remarkable; for example, modern transistors in advanced microchips measure only around 5-10 nanometers in size—roughly 10,000 times smaller than the diameter of a human hair [x]. Integrated circuits can contain billions of transistors on a chip no larger than a few square centimeters, highlighting the level of precision and miniaturization achievable through semiconductor technology [x]. The minuscule size and precision of these components make them essential for modern electronics where space and efficiency are paramount.

*1.1.3.* ***Types of Semiconductor Devices:*** Integrated circuits (ICs) and microchips are crucial in computing and data storage, powering devices such as computers, smartphones, and servers. Diodes control current flow, making them essential for power conversion, signal modulation in communications, and efficient lighting in LED displays. Semiconductor technology also includes light-emitting diodes (LEDs) for high-efficiency lighting, photodetectors for optical communications and medical imaging, and photovoltaic cells, which convert sunlight into electricity for renewable energy applications. These components illustrate the versatility of semiconductor technology.

Fig. 4 An Intel microprocessor


Fig. 5 LED display screen of a Samsung TV


Fig. 6 A solar panel with photovoltaic cells

TABLE I
Examples of Common Semiconductor Devices and Their Applications

| ***Device*** | ***Usage*** | ***Industry*** | ***Semiconductor Type*** |
|---|---|---|---|
| Integrated Circuits (ICs) | Data processing, storage in devices like smartphones, computers | Computing, Telecommunications | Silicon, doped with phosphorus/boron for n/p-type regions |
| Microchips | Powering electronic devices (smartphones, home appliances) | Consumer Electronics, Medical | Silicon, CMOS technology |
| Diodes | Current control in power adapters, signal modulation in radios | Power, Communications | Silicon, Gallium Arsenide, pn-junction |
| LEDs | High-efficiency lighting (LED bulbs), displays in TVs and phones | Lighting, Displays | Gallium Nitride, Gallium Arsenide, doped for color output |
| Photodetectors | Receiving optical signals in fiber optic cables, medical imaging | Telecommunications, Medical | Silicon, Germanium, PIN or avalanche photodiodes |
| Photovoltaic Cells | Solar energy conversion (solar panels) | Renewable Energy | Silicon, Cadmium Telluride, heterojunction structures |
| Silicon-Controlled Rectifiers (SCRs) | AC/DC conversion in industrial machinery, power tools | Industrial Automation, Power Systems | Silicon, high-power applications |
| Charged-Coupled Devices (CCDs) | Image capture in cameras, telescopes | Photography, Medical Imaging, Astronomy | Silicon, specialized photodiode arrays |

## 1.2. Overview of the Semiconductor Electronics Industry Globally

### *1.2.1. Global Supply Chains & Demand, Production Capabilities:*

### *1.2.2. Geopolitical Challenges and Their Impact on the Semiconductor Electronics Industry:*

## 1.3. India's Semiconductor Electronics Industry and Future Projections

### *1.3.1. History & Current Scenario of Semiconductor Electronics Industry in India:*

*1.3.2.* ***Government Initiatives Supporting Domestic Manufacturing:*** The Semicon India Program was launched in December 2021 under the Ministry of Electronics and Information Technology (MeitY) as part of the India Semiconductor Mission (ISM). This initiative aims to position India as a significant player in the global semiconductor ecosystem by promoting domestic manufacturing, attracting investments, and fostering advanced semiconductor research and development. In addition to MeitY, the program collaborates with state governments and industry associations to provide comprehensive support to companies establishing semiconductor manufacturing facilities within India. [7]

*Collaborating Ministries.* The Semicon India Program is closely aligned with other central government ministries, including the Ministry of Commerce and Industry and Ministry of Finance, to streamline incentives and facilitate policy support for semiconductor manufacturing. [7]

*State Partnerships.* As of September 2024, Several state governments, such as Uttar Pradesh, Gujarat, Assam, Karnataka, Odisha, and Tamil Nadu, have shown interest in the program. These states provide additional support, including land and infrastructure facilities, to attract semiconductor investments. [6]

*Key Industry Partnerships.* Major semiconductor companies such as Foxconn, Micron Technology, PSMC and Applied Materials have expressed commitments to invest in India under this program. These partnerships are integral to building a robust and self-sufficient semiconductor supply chain. [7]

*Financial Incentives.* The Semicon India program provides financial support covering up to 50% of the project cost for setting up semiconductor fabs in India, significantly reducing the initial investment burden on companies. This support applies to Silicon and Compound Semiconductor fabs and extends to advanced packaging and testing facilities. [7]

*Infrastructure Support through EMC 2.0.* The Electronics Manufacturing Clusters 2.0 (EMC 2.0) initiative complements the Semicon India Program by creating shared infrastructure hubs. These clusters offer facilities like clean rooms, water treatment plants, and power supply systems, helping companies manage setup costs and enhance operational efficiency. [7]

*Demand Aggregation through Public Procurement.* The program supports the local semiconductor market by offering purchase preferences for domestically produced semiconductor products under the Public Procurement (Preference to Make in India) Order 2017. This creates a stable domestic demand base, encouraging local production and reducing dependence on imports. [7]

*Research and Development Support.* Up to 2.5% of the program's budget is allocated to research and development and workforce training, encouraging partnerships between academic institutions and industry to support talent development and foster innovation. [7]

*Additional Incentives through PLI and DLI Schemes.* Alongside the Semicon India Program, the government offers incentives through the Production-Linked Incentive (PLI) Scheme and the Design-Linked Incentive (DLI) Scheme, which together support semiconductor R&D, manufacturing, and design activities by providing financial assistance and promoting innovation. [7]

### 1.3.3. *India's Potential Role in the Future Global Semiconductor Landscape:*

## 1.4. Introduction to Architecture of Semiconductor Manufacturing FABs

### 1.4.1. *Defining Semiconductor Manufacturing FABs and Their Function:*

Semiconductor manufacturing FABs, or "fabrication facilities," are specialized plants where semiconductor devices are produced. These facilities operate under stringent environmental controls to ensure the precision, cleanliness, and reliability required for high-quality device fabrication.

### 1.4.2. *Important Terminologies and Concepts:*

This section defines key terms essential for understanding semiconductor manufacturing FABs and their architecture. These terms, used throughout the paper, are critical for grasping the technical processes and design considerations of these facilities.

***Semiconductor.*** A material with electrical conductivity between that of a conductor and an insulator, such as silicon, germanium, or gallium arsenide. Semiconductors are the foundation of modern electronics, enabling the creation of components like diodes, transistors, and integrated circuits.

***Semiconductor Electronics.*** Devices and systems built using semiconductor materials, including transistors, diodes, and integrated circuits. These electronics power everything from consumer gadgets to advanced systems like AI, telecommunications, and robotics.

***FAB.*** Short for 'Fabrication Plant' is a commonly used term for a specialized facility where semiconductor devices are manufactured. FABs house cleanrooms, which have advanced machinery that produce or fabricate microchips.

***Cleanroom.*** A controlled environment (usually a large hall) with extremely low levels of airborne particles and contaminants. Cleanrooms are vital in FABs to prevent defects in the semiconductor devices that may be caused by contamination during the manufacturing processes.

***Contamination.*** The presence of unwanted particles, chemicals, or biological materials in a cleanroom environment that can interfere with the semiconductor manufacturing process. Contaminants can range in size from macroscopic particles to microscopic and submicroscopic particles. Particles as small as 0.1 microns (100 nanometers) can be considered contaminants in advanced semiconductor processes. Even these minute particles can cause defects in circuits, reducing yield and impacting device reliability. Effective contamination control is critical, involving air filtration, cleanroom protocols, and ultrapure materials.

***Cleanliness Classifications (Class).*** Cleanroom classifications define the maximum allowable particle counts per unit volume of air, ensuring appropriate cleanliness levels for sensitive processes like semiconductor manufacturing. These classifications are based on two widely used systems:

1) ISO Classifications (ISO 14644-1:2015):
    - Developed as an international standard for cleanroom classifications to ensure global uniformity.
    - Specifies particle counts per cubic meter of air for various particle sizes.
    - Example nomenclature: ISO Class 5 cleanroom.

TABLE II

ISO 14644-1 Cleanroom Classifications and their Particle Concentrations [10]

| ***Class*** | ***Number of Particles per Cubic Meter by Micrometer Particle Size*** | | | | | |
|---|---|---|---|---|---|---|
| | **0.1 µm** | **0.2 µm** | **0.3 µm** | **0.5 µm** | **1 µm** | **5 µm** |
| **ISO 1** | 10 | 2 | - | - | - | - |
| **ISO 2** | 100 | 24 | 10 | 4 | - | - |
| **ISO 3** | 1,000 | 237 | 102 | 35 | 8 | - |
| **ISO 4** | 10,000 | 2,370 | 1,020 | 352 | 83 | - |
| **ISO 5** | 100,000 | 23,700 | 10,200 | 3,520 | 832 | 29 |
| **ISO 6** | 1,000,000 | 237,000 | 102,000 | 35,200 | 8,320 | 293 |
| **ISO 7** | NA | NA | NA | 352,000 | 83,200 | 2,930 |
| **ISO 8** | NA | NA | NA | 3,520,000 | 832,000 | 29,300 |
| **ISO 9** | NA | NA | NA | 35,200,000 | 8,320,000 | 293,000 |

2) Federal Standard 209E (FS 209E):
    - Developed by the U.S. government and primarily used in the U.S., it was deprecated in 2001 but is still commonly referenced.
    - Specifies particle counts per cubic foot of air, with a focus on particles ≥0.5 µm.
    - Example nomenclature: Class 100 cleanroom.

TABLE III

ISO 14644-1 & FS 209E Class Equivalence Comparison [10]

| ISO 14644-1 Class | FS 209E Class |
|---|---|
| 1 | NA |
| 2 | NA |
| 3 | 1 |
| 4 | 10 |
| 5 | 100 |
| 6 | 1,000 |
| 7 | 10,000 |
| 8 | 100,000 |

***Vibration Isolation.*** Techniques to minimize or eliminate vibrations that can disrupt the precision required in semiconductor manufacturing machines. Sources of vibration can include mechanical equipment (e.g., HVAC systems, pumps, compressors), vehicular traffic and external environmental factors such as seismic activity.

Semiconductor manufacturing tools, such as lithography machines, rely on precise laser or electron beams to print nanometer-scale circuits on the wafers. Even the smallest vibrations can cause misalignment of these beams, leading to defects, reduced yields, and compromised device functionality, making vibration isolation critical to ensuring high-quality production.

***Vibration Criteria (VC).*** A system of classification that specifies maximum allowable vibration velocities of the structure to ensure the operational precision of vibration-sensitive equipment. The graph below highlights the significantly lower acceptable vibration levels required for FAB structures compared to the structures we encounter in daily life. Depending on the sensitivity of the equipment, FABs in general require VC-B or below vibration criteria.

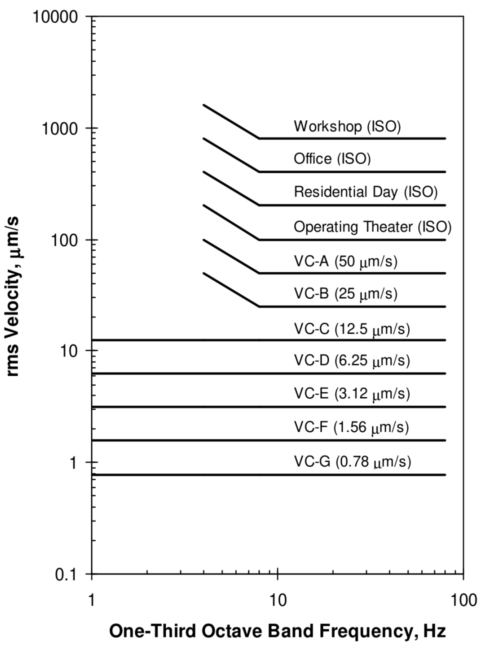



Fig. 7 Generic vibration criterion (VC) curves for vibration-sensitive equipment, showing also the ISO guidelines for people in buildings [20]

| Criterion | Definition |
|---|---|
| VC-A | 260 µg between 4 Hz and 8 Hz; 50 µm/s (2000 µin/s) between 8 Hz and 80 Hz |
| VC-B | 130 µg between 4 Hz and 8 Hz; 25 µm/s (1000 µin/s) between 8 and 80 Hz |
| VC-C | 12.5 µm/s (500 µin/s) between 1 and 80 Hz |
| VC-D | 6.25 µm/s (250 µin/s) between 1 and 80 Hz |
| VC-E | 3.1 µm/s (125 µin/s) between 1 and 80 Hz |
| VC-F | 1.6 µm/s (62.5 µin/s) between 1 and 80 Hz |
| VC-G | 0.78 µm/s (31.3 µin/s) between 1 and 80 Hz |

TABLE IV. Numerical definition of criterion curves shown in Figure 7 [20]

***Seismic Stability.*** Refers to site locations with minimal vibrations originating from the movement or collision of tectonic plates and a very low probability of earthquakes. In India, the landmass is categorized into seismic zones, with Zone II and Zone I considered the safest in terms of seismic activity. Additionally, structural methods such as vibration isolation of the foundation, shock-absorbing rubber sheets, and similar techniques are employed to counteract minimal ground vibrations.

***Electromagnetic Interference (EMI).*** Electromagnetic disturbances that can affect the operation of sensitive FAB equipment. Sources of EMI include nearby power lines and motors. Shielding and grounding techniques are used to mitigate these effects.

***EMI Shielding.*** The use of conductive or magnetic materials to block or reduce electromagnetic interference, ensuring the consistent performance of semiconductor manufacturing processes.

***Laminar Flow.*** A smooth, unidirectional airflow in cleanrooms, typically directed from the ceiling to the floor. This airflow sweeps particles downward and then are captured by high-efficiency particulate air (HEPA) filters or ultra-low particulate air (ULPA) filters, ensuring effective removal of contaminants and maintaining cleanliness.

***Wafer.*** A thin, circular slice of semiconductor material, such as silicon, used as the base substrate for fabricating integrated circuits. Wafers are typically 0.5 to 1.5 mm thick and come in standard diameters of 200 mm (8 inches), 300 mm (12 inches), and 450 mm (18 inches). FABs generally specialize in one of these sizes.

***Critical Dimension (CD).*** The smallest feature size that can be reliably created on a semiconductor wafer. Smaller dimensions are more challenging to manufacture, requiring highly advanced FABs. In modern chips, the critical dimension can be as small as 3 nanometers (nm), with research progressing toward 2 nm and below.

***Integrated Circuit (IC).*** A microchip that integrates millions or billions of electronic components such as transistors, resistors, and capacitors onto a small piece of silicon. ICs perform functions like computation, signal processing, and data storage.

***Transistor.*** A semiconductor device used to amplify or switch electronic signals. Transistors are fundamental building blocks of modern electronic circuits and are integral to ICs.

***Frontend Process.*** The stage of semiconductor manufacturing where electronic circuits are created on silicon wafers in specialized fabrication facilities.

***Backend Process.*** The stage where the completed wafers are cut into individual chips, packaged, connected, and tested to prepare them for use in electronic devices.

***Effluent Treatment.*** The process of managing and treating wastewater and chemical waste generated during semiconductor manufacturing. Effluent treatment involves steps like neutralization, filtration, and chemical recovery to minimize environmental impact and meet regulatory standards. FABs often have dedicated Effluent Treatment Plants (ETPs) to handle the specific contaminants from manufacturing processes. By effectively managing waste, a well-designed FAB can become nearly completely non-polluting, significantly eliminating its negative environmental footprint.

## 1.5. The Role of the Architect in Semiconductor Manufacturing Facility Design

The architect's role in designing a semiconductor FAB extends beyond creating functional spaces—it involves integrating technical precision with human-centric design and aesthetic value. Unlike conventional industrial buildings, FABs demand an extraordinary level of precision, cleanliness, and environmental control. Architects bring a holistic vision, ensuring that these highly technical requirements align with the broader goals of efficiency, sustainability, and user well-being.

*1.5.1.* ***Leadership in Collaboration:*** Architects also play a crucial leadership role in multidisciplinary teams, working closely with engineers, project managers, and other stakeholders. They ensure that technical specifications for utilities, cleanrooms, and support systems integrate seamlessly into the overall design. This collaborative approach ensures that all aspects of the project—from structural stability to utility access—are coordinated without compromising on design or functionality.

1.5.2. ***Integrating Functional and Aesthetic Elements in FABs:*** Semiconductor FABs are spaces where precision engineering meets advanced manufacturing, requiring architects to blend function with form. Architects address challenges like integrating cleanroom requirements, vibration isolation, and EMI shielding within aesthetically appealing and user-friendly environments. This not only enhances the operational effectiveness of the facility but also creates an engaging and inspiring environment for its users.

1.5.3. ***Human-Centered Design in Industrial Architecture:*** In FABs, where contamination control, vibration isolation, and electromagnetic shielding are critical, architects design spaces that seamlessly integrate these technical requirements while addressing the significant physical and psychological challenges faced by engineers working in demanding cleanroom environments. Thoughtful design elements such as natural lighting where possible, ventilation, and ergonomic layouts not only enhance functional efficiency but also prioritize the well-being and comfort of occupants, fostering productivity and a more pleasant working experience.

1.5.4. ***Creating Iconic Architectural Landmarks for the Semiconductor Industry:*** Architects are uniquely positioned to imbue industrial facilities with symbolic value. Semiconductor FABs are often national assets, and their design can reflect technological progress and national pride. By using innovative forms, sustainable materials, and aesthetic detailing, architects ensure these buildings are not just functional but iconic, representing the cutting-edge nature of the industry.

## 2. The Importance of Architectural Design and Aesthetics in Industrial Facilities

“Although industrial buildings are not a new building typology, industrial architecture was not always, so to say, ‘present’ in construction of industrial facilities.”[8] Historically, industries were major sources of pollution, noise, and environmental degradation. While modern advancements have significantly reduced these impacts, the perception of industrial facilities as visually unappealing, detrimental, and intrusive still persists. This has traditionally led to their isolation in remote locations, far from urban centers, reinforcing the notion that industrial facilities were necessary evils—functional structures disconnected from the societal and environmental fabric. However, as industries continue to evolve to meet modern demands, this outdated perception is gradually shifting, paving the way for more aesthetically thoughtful, and human-centric industrial design.

Today, the role of architectural design in industrial facilities extends far beyond basic functionality. Modern industries are integral to both the community and the environment, requiring spaces that reflect their significance and foster a strong sense of identity. Through thoughtful design, architects can transform industrial facilities into visually striking structures. These buildings have the potential to serve as symbols of technological advancement and national progress, bridging the gap between industrial necessity and architectural beauty.

Architects are key players in this transformation, showcasing how aesthetic and user experience principles can enhance industrial spaces. While industrialists and investors often prioritize direct functionality, they may overlook the broader benefits of architectural design. Well-designed facilities not only improve operational efficiency but also create environments that boost worker productivity, promote well-being, and strengthen community connections. By integrating natural landscape elements, ergonomic spaces, and visually engaging designs, architects ensure that industrial buildings contribute positively to the human experience, aligning technological innovation with human and environmental needs.

All Industries need not be viewed as environmental burdens. Technological advancements have enabled practices such as effluent treatment, material recycling, cleaner energy sources, enhanced worker health and safety, and responsible waste disposal. The emergence of non-polluting, environmentally conscious industries demonstrates a shift toward sustainability, a standard that must become the norm in industrial development.

Emerging sectors like semiconductor electronics manufacturing present an opportunity to set new benchmarks in industrial architecture. These facilities can combine technical precision with thoughtful design and human-centric principles, creating iconic structures. By doing so, they highlight the increasing role of architectural innovation in shaping the future of industrial facilities.

### 2.1. Exemplary Industrial Architecture

This section highlights notable examples of industrial facilities that seamlessly blend functionality with striking architectural design. By showcasing these examples, we can better appreciate the potential of thoughtful design in industrial spaces. Seeing what has been achieved elsewhere helps us understand how such facilities can transcend pure functionality to become defining landmarks, offering inspiration for envisioning semiconductor FABs that symbolize innovation and progress.

Fig. x Factory in the Forest, Paramit Corporation, Penang, Malaysia, designed by Design Unit Architects Sdn Bhd. Used for manufacturing and research of medical devices and life science equipment.

Fig. x TSMC Fab 14, Taiwan Semiconductor Manufacturing Company, Shanhua District, Tainan City, Taiwan. Designed by JJP Architects and Planners, used for semiconductor electronics manufacturing.

Fig. x. Wolfsburg Volkswagen Plant. Designed by Volkswagen's in-house team, used for vehicle manufacturing and company headquarters.

Fig. x. BMW Central Building, Leipzig, Germany. Designed by Zaha Hadid, serving as the central hub for BMW's vehicle production operations.

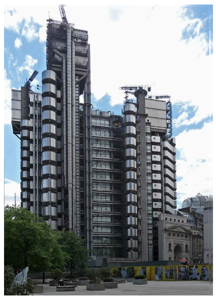
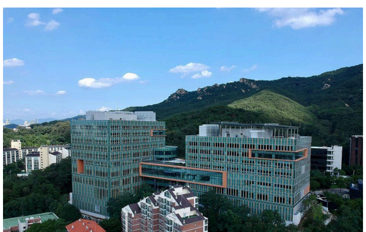


Fig. x. Lloyd's Building, London, UK. by Richard Rogers & Partners

Fig. x. Extension Nestlé Research Center, Nestlé, Lausanne, Switzerland. Designed by Burckhardt+Partner, used for food science research and development.

Fig. x. Volkswagen Transparent Factory, Volkswagen Group, Dresden, Germany. Designed by Gunter Henn, used for vehicle assembly and visitor engagement.

Fig. x. McLaren Technology Centre, McLaren Group, Woking, UK. Designed by Foster + Partners, used for automotive manufacturing and research operations.

## 3. Overview of Semiconductor Electronics FABs

This section provides a foundational understanding of semiconductor electronics FAB facilities, detailing their purpose, core components, and the critical role of cleanrooms. It explores the main FAB building alongside supporting utility structures and categorizes FABs based on the type of semiconductor electronics they produce, their scale, and whether they are designed for manufacturing or research purposes. Additionally, it outlines the generic manufacturing process, offering insight into the sequence of operations within these specialized facilities.

### 3.1. What is a FAB?

A semiconductor fabrication plant, commonly known as a 'FAB,' is a highly advanced facility where a wide range of semiconductor devices are manufactured. These include microchips, diodes, transistors, and integrated circuits, which are integral to modern technology.

At the core of every FAB are cleanrooms—specially controlled environments where semiconductor wafers are processed, and circuits are printed. These cleanrooms form the backbone of the semiconductor manufacturing process, ensuring the precision and reliability required for devices used in critical applications.

FABs are equipped with some of the most sophisticated machinery in the world, designed for processes such as lithography, etching, doping, and deposition. These tools enable the production of semiconductor devices tailored for diverse applications. The scale and complexity of these facilities are reflected in their significant investments—Intel, for example, reports spending over $12 billion to construct a single FAB, underscoring the technological and economic importance of these facilities. [11]

### 3.2. Components of a FAB Facility

A semiconductor fabrication facility has an intricate assembly of systems and infrastructure working in concert to enable the precision manufacturing of semiconductor devices. The main components of a FAB include the Main FAB Building, Cleanrooms, Utility Systems, Material Handling Systems, Control Room, and Support Facilities.

*3.2.1.* ***Main FAB Building & Cleanrooms:*** Cleanrooms are the most critical component of the main FAB building, and are where the manufacturing processes take place. Cleanrooms are maintained under strict conditions, including controlled air purity, temperature, humidity, and vibration, to ensure defect-free production and maintain the reliability of the devices manufactured.

Fig. x Image of a semiconductor research fab cleanroom with perforated ceiling and floor tiles, sourced from Berkeley Lab New Center [15]

Fig. x Image of a semiconductor research fab cleanroom, sourced from Pro-Fab Cleanrooms [16]

*Air Purity.* Air purity is a critical aspect of semiconductor cleanrooms, as even microscopic particles can disrupt the intricate manufacturing processes. The air purity or concentration of particle contaminants are categorized into classes based on ISO 14644-1 standards, which define the maximum allowable concentration of particles of specific sizes per cubic meter of air. Cleanrooms follow these classifications to maintain the ultra-clean environments necessary for semiconductor manufacturing. Common systems for achieving air purity include laminar flow systems, which direct air uniformly from ceiling to floor to remove contaminants, and recirculating airflow systems, which continuously filter and redistribute air to maintain cleanliness. [14]

*Temperature.* Temperature in semiconductor cleanrooms is maintained at a strict range, typically around 23±0.5°C, to ensure process stability and product quality. This control is critical for several reasons: [14]

- *Thermal Stability:* Consistent temperature minimizes thermal expansion or contraction, which could disrupt the precision required for nanometer-scale semiconductor processes.
- *Chemical Reaction Consistency:* Many semiconductor processes, such as photolithography and chemical vapor deposition, depend on exact thermal conditions to ensure uniform reactions and consistent material properties.
- *Avoidance of Equipment Misalignment:* Slight temperature variations can cause misalignment of manufacturing tools, impacting the integrity of printed circuits.

*Humidity.* Humidity levels in cleanrooms are tightly controlled, typically within the range of 35-45% relative humidity (RH). [13] High humidity can cause condensation, leading to corrosion of sensitive components and potential electrical shorts. On the other hand, low humidity increases the risk of static electricity buildup, which can result in sudden discharges that damage components and disrupt manufacturing operations. Maintaining the ideal humidity range ensures the protection of both the equipment and the semiconductor devices, minimizing defects and enhancing production yields. [12]

*Vibration.* Vibration control is critical in semiconductor manufacturing due to the nanometer precision required for processes like lithography and etching. Even slight vibrations can misalign machinery and lead to defects in the circuits printed on silicon wafers. To address this, FABs are often located in regions with low seismic activity and employ vibration isolation systems, such as dampening mounts and specialized foundation designs, to minimize the impact of both external and internal vibrations. This ensures the stability and accuracy of manufacturing operations.

### 3.2.2. ***Utility Systems:***

*Ultra-Pure Water (UPW) System.* Provides extremely pure water for cleaning and rinsing wafers, ensuring no contamination during manufacturing.

*Cooling Water System.* Dissipates heat generated by machinery and equipment, maintaining operational efficiency and preventing overheating.

*Chiller System.* Cools water and air for HVAC systems to regulate cleanroom temperature and humidity.

*Heating, Ventilation, and Air Conditioning (HVAC) System.* Maintains temperature, humidity, and cleanroom air purity.

*Compressed Dry Air (CDA) System.* Supplies clean, moisture-free air for equipment operation and maintaining particle-free conditions.

*Vacuum System.* Generates high vacuum environments essential for etching, deposition, and wafer handling.

*Gas Delivery System.* Ensures precise and safe supply of specialty gases required for semiconductor processes.

*Power Supply System.* Ensures a stable electricity supply through grid power as the primary source, backup generators for emergencies, and uninterruptible power supply (UPS) systems to maintain continuity during power fluctuations or outages.

*Chemical Distribution System.* Manages delivery of chemicals to tools and safely disposes of hazardous by-products.

*Exhaust and Scrubber Systems.* Removes hazardous emissions and treats them to comply with safety and environmental standards.

*3.2.3.* ***Support Facilities:*** Support facilities in a semiconductor FAB include offices for administrative and engineering staff, laboratories for testing and quality control, and storage areas for raw materials and tools. These facilities also house safety systems, such as fire suppression and emergency response units, ensuring compliance with safety standards. Additional spaces like break rooms and training areas support workforce functionality and development.

*3.2.4.* ***Control Room & Monitoring Systems:*** The control room monitors and manages the FAB's operations, collecting data from tools, utility systems, and cleanrooms through Supervisory Control and Data Acquisition (SCADA) and Manufacturing Execution Systems (MES). It enables real-time tracking of processes, identification of issues, and immediate intervention to maintain manufacturing precision and prevent disruptions.

## 3.3. Types of FABs

In this section, semiconductor fabrication facilities (FABs) are categorized based on their purpose, such as research or high-volume manufacturing, as well as their architectural layout and operational workflows. These classifications are determined by factors such as production scale, levels of automation, and cleanroom design. Understanding these distinctions highlights the unique architectural requirements of each type of FAB.

### *3.3.1. Types of FABs Based on Functionality:*

*Manufacturing FABs.* Large-scale facilities ($\sim10^5$ to $10^6$ ft²) designed for mass production of semiconductors, typically employing advanced automation with minimal human presence in cleanrooms. Processes are streamlined within expansive, centralized spaces to maximize efficiency.

*R&D FABs.* Smaller facilities ($\sim10^4$ to $5\times10^4$ ft²) focused on prototyping and testing new semiconductor technologies. They feature segmented spaces to house diverse processes, with manual handling of materials and a higher density of engineers operating the equipment.

*Pilot FABs.* Transitional facilities that test and scale up new technologies developed in R&D FABs before moving to full-scale manufacturing. These FABs often blend features of both R&D and manufacturing facilities.

### *3.3.2. Types of FABs Based on Cleanroom Layout:*

*Ballroom Layout.* Features a single, large cleanroom space where most tools and processes are located. This layout minimizes airflow turbulence and is ideal for high-volume production facilities.

*Bay-and-Chase Layout.* Cleanrooms are divided into bays connected by service chases. This design isolates different processes, reduces cross-contamination, and is often used in R&D FABs.

*Podular Layout.* Cleanrooms are divided into smaller, modular sections to accommodate highly specialized or varied processes. This layout provides flexibility for both R&D and niche manufacturing.

*Tunnel Layout.* Equipment and processes are arranged in linear, tunnel-like configurations, optimizing material flow in automated manufacturing setups.

## 3.4. Overview of Manufacturing Processes

The manufacturing of semiconductor devices involves a sequence of repetitive and precise processes to construct intricate structures on wafers layer by layer. These processes are used cyclically, often dozens or even hundreds of times, to build multilayered chips with millions or billions of transistors. For example, a modern microprocessor may pass through 500-1000 process steps and require 30-40 cycles of photolithography and etching to create its various layers. This process can take weeks to complete for a single batch of wafers. During manufacturing, Front Opening Unified Pods (FOUPs) transport wafers between tools, moving on automated tracks (called Overhead Hoist Transfer systems, OHT) to ensure efficient and contamination-free handling. Once the chip layers are constructed, wafers are diced into individual chips, and interconnects are added to enable communication between components.

### 3.4.1. ***Manufacturing Processes:***

*Wafer Preparation.* The process begins with silicon wafers being sliced, polished, and cleaned to create a flat, contamination-free surface.

*Oxidation.* A thin oxide layer is grown on the wafer surface to act as an insulating layer, typically using thermal oxidation methods.

*Photolithography.* Patterns are transferred onto the wafer using a photoresist material and ultraviolet (UV) light through a mask. This step defines the layout of circuit features.

*Etching.* Unwanted material is removed to create patterns in the wafer. Wet etching or dry plasma etching is used based on the process requirements.

*Doping/Ion Implantation.* Impurities are introduced into specific areas of the wafer to modify its electrical properties, enabling the creation of transistors.

*Deposition.* Layers of materials, such as metals, dielectrics, or semiconductors, are deposited on the wafer using techniques like Chemical Vapor Deposition (CVD) or Physical Vapor Deposition (PVD).

*Chemical Mechanical Planarization (CMP).* Excess material is polished away to achieve a flat, uniform surface before the next layer is added.

*Interconnect Formation.* Metal layers are deposited and patterned to create the connections between the transistors and other circuit components.

*Dicing and Packaging.* After all layers are complete, the wafer is diced into individual chips. These chips are packaged and connected to external circuitry.

*Testing and Inspection.* Chips undergo electrical testing to ensure functionality and reliability before being shipped for assembly into devices.

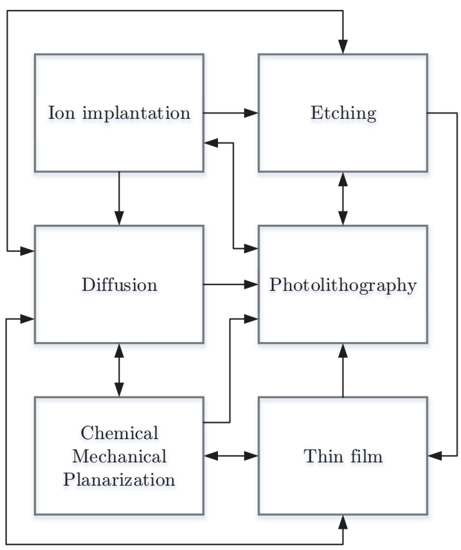



Fig. x  Abstract Process Flow of Typical Semiconductor Manufacturing [17]

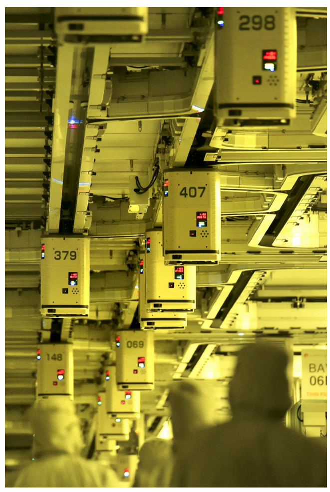



Fig. x  FOUPs, transport silicone wafers overhead in the clean room at GlobalFoundries Fab 8. [18]

## 4. Site Selection for FAB Facilities

Selecting an optimal site for a semiconductor manufacturing facility, or FAB, is crucial to ensure efficient, sustainable, and uninterrupted operations. The fabrication process is highly sensitive, requiring a stable environment, access to essential resources, and robust logistical support. This section outlines the critical factors that architects and planners should consider when identifying potential sites, setting the foundation for an effective and future-proof semiconductor production facility.

### 4.1. Regional Site Selection Factors

#### *4.1.1. Environmental Stability:*

*Seismic Stability.* Semiconductor FABs are sensitive to vibrations, requiring low seismic risk areas to prevent disruptions and equipment damage. Ideal sites fall under seismic Zone II or lower on the Indian seismic zoning map, which corresponds to regions with peak ground acceleration (PGA) values below 0.15 g. [x]

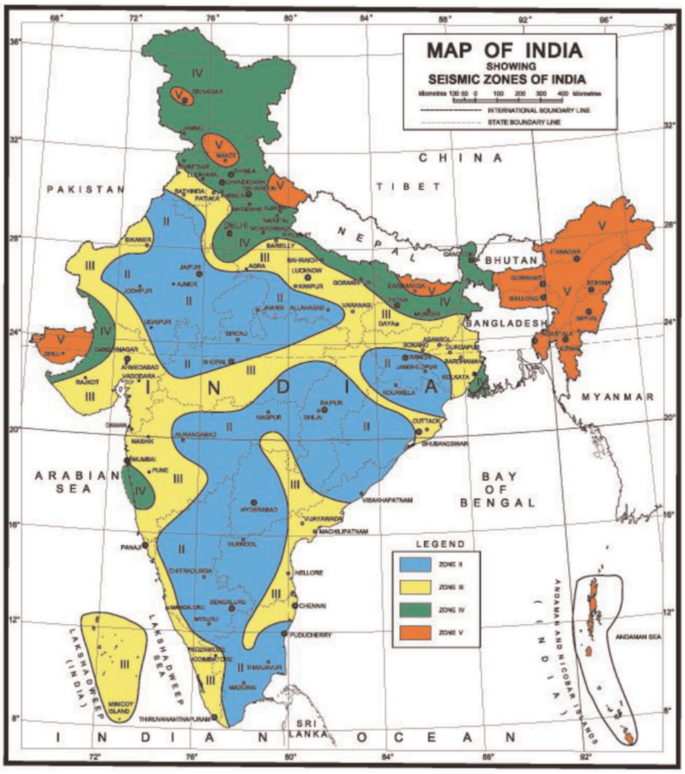



Figure 7: Indian Seismic Zone Map as per BIS 1893 (Part 1): 2016
[Map taken from BIS 1893 (Part 1): 2016, Sixth Revision].

*Temperature Control.* Moderate temperatures are essential to maintain stable equipment performance and reduce cooling demands. The preferred temperature range is 20–25°C (68–77°F). [x]

*Humidity Levels.* Humidity is ideally controlled between 35-45% relative humidity to prevent issues with static electricity and moisture that could interfere with semiconductor processes. Cleanrooms maintain even tighter humidity controls within this range. [13]

### 4.1.2. *Resource Proximity:*

*Water Supply.* Semiconductor FABs are highly water-intensive, requiring 2 to 4 million gallons per day of ultrapure water (UPW) for cleaning, cooling, and etching processes. For example, TSMC in Taiwan consumes around 156,000 cubic meters (41 million gallons) of water daily across its facilities [x]. Sites are ideally located near abundant and reliable water sources, like rivers or lakes, to ensure consistent supply. [x]

*Water Types Needed.* Ultra-pure water, essential for processes like wafer cleaning, must undergo multiple purification stages to achieve the required purity, with 1,400 to 1,600 gallons of municipal water needed to produce 1,000 gallons of UPW. [x]

*Chemical Accessibility.* FABs rely on several types of specialized chemicals, including acids, bases, dopant gases, etching gases, and oxidizers. Each of these chemical types plays a specific role in processes such as cleaning, etching, doping, and layer deposition essential to semiconductor electronics manufacturing. Proximity to existing industrial zones where these chemicals are already distributed can simplify the supply chain and reduce costs. [x]

### 4.1.3. *Infrastructure and Logistical Accessibility:*

*Electricity Power Supply.* Power requirements for semiconductor FABs are substantial. For instance, Intel's FAB 42 in Arizona, focused on advanced microprocessor production, consumes around 60-100 megawatts per hour, equivalent to the energy needed to power about 80,000-100,000 homes. A constant and uninterrupted power supply is essential for semiconductor manufacturing due to the sensitivity of the equipment and processes. Ideally, a dedicated grid supply specifically allocated to the FAB ensures stable energy access. Additionally, on-site generators, battery storage systems, and uninterruptible power supplies (UPS) are standard to provide backup during grid fluctuations or outages, minimizing the risk of operational disruptions. [x]

*Transportation and Export Facilities.* Efficient import of raw materials, like silicon wafers, and export of high-value semiconductor products are essential for FABs. Proximity to major airports, ports, and highways minimizes logistical delays and costs, supporting global distribution. Additionally, FABs should be well-connected to the rest of the supply chain, including facilities where semiconductor chips are assembled onto printed circuit boards (PCBs) and integrated into electronic devices. This seamless connectivity with downstream assembly and manufacturing sites helps streamline production, reduce lead times, and support efficient distribution in the global market. [x]

### 4.1.4. *Availability of Skilled Workforce:*

*Qualified Labor Requirements.* FABs demand a highly skilled workforce, including engineers, technicians, and operators with specialized training. A minimum qualification of a bachelor's degree in engineering (electrical, mechanical, or chemical) is standard for technical roles, and proximity to technical universities and vocational training centers is advantageous to support ongoing skill development. [x]

*Proximity to Educational Institutions.* Selecting a site near technical universities or vocational training centers is ideal, as they supply a continuous stream of trained professionals for hiring and skill development.

### 4.1.5. *Government Initiatives and Regulatory Environment:*

*Semicon India.* The Semicon India Program, as outlined in the guidelines for establishing semiconductor fabs in India, provides targeted support that directly impacts site selection for FABs. The program offers up to 50% fiscal support for infrastructure costs, including essential site utilities such as dedicated water and power supply, crucial for uninterrupted manufacturing. Additionally, it promotes the development of Electronics Manufacturing Clusters (EMC 2.0), which provide shared infrastructure and reduce logistical costs associated with sourcing materials and exporting products. This support framework, detailed in the Semicon India guidelines, encourages site selection in regions with government-backed infrastructure, enabling fabs to operate efficiently within a robust, well-connected ecosystem.

*Production-Linked Incentive (PLI) Scheme for Semiconductors.* The PLI Scheme was introduced in December 2021 with a budget of $10 billion to support the development of semiconductor and display manufacturing facilities. This includes subsidies for setting up fabrication units, packaging, and testing facilities.

*Special Economic Zones (SEZs) and Industrial Zones.* Semiconductor manufacturing facilities can be established in Special Economic Zones (SEZs) to benefit from tax exemptions, customs duty reductions, and relaxed regulatory processes. For example, Gujarat's Dholera Special Investment Region (DSIR) has been earmarked as a prime location for semiconductor FABs due to its incentives and proximity to logistics hubs.

### 4.2. On-Site Selection Considerations

*4.2.1.* ***Topography and Land Condition:*** The site should be a large, flat, and stable land area with minimal slope. This minimizes groundwork requirements and ensures efficient construction of extensive cleanroom spaces and production facilities.

*4.2.2.* ***Site Size and Layout Flexibility:*** The size of semiconductor FAB sites varies widely, primarily depending on production scale, technology requirements, and facility complexity. For example, TSMC's advanced semiconductor facility in Phoenix, Arizona, spans around 1,128 acres and includes extensive infrastructure to support high-volume, cutting-edge 5nm and 3nm chip production.

In contrast, a smaller, specialized facility like Tower Semiconductor's FAB in Migdal HaEmek, Israel occupies approximately 20 acres and focuses on niche applications such as analog and RF (Radio Frequency) chips. Large fabs often require extensive cleanrooms, high-capacity utilities, and space for future expansion, while smaller fabs prioritize compact setups and simpler infrastructure to support less complex manufacturing needs.

A flexible site layout is essential for semiconductor FABs to accommodate future expansions, adapt to evolving technology needs, and ensure efficient material flow. This flexibility supports modular expansions, efficient zoning for safety and utility placement, and adaptable spaces for auxiliary facilities like R&D labs, helping the FAB respond to industry advancements and operational changes seamlessly.

*4.2.3.* ***Water Management and Storage Potential:*** Sites with natural depressions or nearby water bodies can be advantageous for rainwater harvesting, on-site water storage, or establishing effluent treatment facilities, aiding in sustainable water usage for the high water demands of a FAB.

*4.2.4.* ***Soil Quality and Load-Bearing Capacity:*** The site should have soil with high load-bearing capacity to support heavy machinery and infrastructure without needing extensive reinforcement, as this contributes to a stable foundation for cleanrooms and equipment.

*4.2.5.* ***Accessibility for Logistics and Material Handling:*** The site should allow for easy access for transportation, material loading and unloading, and internal site movement, ideally with provisions for multiple entry and exit points to enhance operational efficiency.

*4.2.6.* ***Environmental Control Capabilities:*** The ability to create and maintain a clean, controlled environment is essential for semiconductor manufacturing. Low particulate contamination is critical, so sites with fewer natural or industrial pollution sources are preferred to reduce the need for extensive filtration.

*4.2.7.* ***Proximity to Emergency Services and Safety Considerations:*** Access to nearby emergency services, such as fire fighting, medical, and safety response units, is critical. Additionally, the site should allow for well-planned emergency exits, evacuation areas, and on-site safety equipment to support the workforce's well-being.

## 5. Site Master Planning of FAB Facilities

The spatial layout of semiconductor FAB facilities is carefully designed to meet the exacting requirements of chip manufacturing. Key zones include the main FAB building with controlled cleanrooms, utility buildings for air filtration, water treatment, chemical supply and power management, as well as administrative offices and

R&D labs for testing. Site planning centers around contamination control, with cleanrooms at the core, supported by nearby utility structures for quick access to ultra-pure water, power, and chemicals. Additionally, FAB site planning must consider factors such as vibration isolation, EMI shielding, and safety zoning for hazardous chemicals, all essential for the functioning of the FAB. This approach ensures that semiconductor facilities can operate with the precision, safety, and efficiency critical to their function.

## 5.1. Buildings and Zones in FAB Facilities

The following is a list of essential buildings and zones recommended for inclusion in a semiconductor electronics manufacturing FAB facility:

- Main FAB Building(s)
- Utility and support buildings - 1) HVAC and Air Filtration Systems, 2) Water Systems, 3) Power Supply and Backup Systems, 4) Chemical Storage and Distribution, 5) Waste Management and Effluent Treatment
- Administrative offices
- Office spaces
- Product storage areas
- R&D and testing labs
- Employee welfare and support areas
- Data center

### *5.1.1. Main FAB Building:*

The Main FAB Building is where semiconductor device manufacturing occurs, housing all necessary machinery within ultra-controlled cleanrooms. Equipped with precision machinery, this building maintains stringent contamination control to protect the nanoscopic manufacturing processes. It is typically located centrally, as the Main FAB Building requires seamless access to utility systems, including HVAC, water, power, chemical supply, and waste management. Designed as a hermetic structure, it protects sensitive processes from vibrations, electromagnetic interference (EMI), and UV light exposure. This building has the unique characteristic of being both isolated from external disruptions while simultaneously well integrated with essential utilities.

*Access to Utilities.* The FAB building is strategically located centrally at site, ensuring close proximity to utility buildings that provide high-capacity power, water, air filtration & HVAC, and chemical supplies. This central positioning minimizes transport distances, supports efficient utility distribution.

*Vibration Isolation.* The FAB building must be located at an adequate distance away from sources of vibration, due to the highly sensitive fabrication processes. In certain cases it may be advantageous to build the FAB underground in areas where surface vibrations are high, as the soil and rock work as dampeners.

Sources of vibration to avoid through site planning:

- Vehicular traffic
- Loud sound
- Rotating Mechanical Equipment in utility buildings:
    1. HVAC systems - fans, blowers, air handlers
    2. Chilled water & cooling systems - chillers, cooling tower fans
    3. Pumps - for water and chemicals
    4. Compressors - air compressors, refrigerant compressors
    5. Power supply systems - Diesel generators

*Electromagnetic Interference.* Electromagnetic interference (EMI) affects the processes of critical machines in semiconductor FABs. These machines are highly sensitive precision tools (e.g., lithography systems, microscopes, and metrology equipment) that rely on accurate beam or particle control for nanometer-level manufacturing and measurement. Even minor electromagnetic interference can disrupt their performance. While methods like shielding and active cancellation are effective, maintaining a safe distance from EMI sources remains highly important.

Sources of Electromagnetic Fields from which the FAB must be built at a safe distance:

- High-power electrical cables and power transmission lines
- Rotating electrical machinery - motors, generators
- Nearby radio-frequency transmitters - mobile towers, communication devices

*5.1.2.* ***Office Buildings:*** Office buildings in a semiconductor FAB facility serve as the administrative and engineering hub, making them ideal for showcasing architectural aesthetics. Office buildings in a semiconductor FAB facility could be positioned at the front of the site or near the main entrance. This placement offers an opportunity to use the office as the architectural face of the facility, as it is subject to fewer restrictions compared to the highly controlled FAB and utility buildings. With more design flexibility, office buildings could feature iconic and aesthetically appealing designs, serving as a landmark for the site.

*5.1.3.* ***Utility Buildings:*** Utility buildings, which house systems such as HVAC chillers, generators, and chemical storage, could be located at a distance from the main FAB building to minimize potential impacts from vibrations and electromagnetic interference. However, these buildings should not be placed too far from the FAB, as they directly supply essential resources like power, water, and chemicals. There is a balance to be achieved, where the distance is sufficient to prevent disruptions to the sensitive FAB processes, yet close enough to ensure efficient and seamless delivery of utilities. The exact placement would depend on the nature and magnitude of disturbances caused by specific equipment and the operational requirements of the facility.

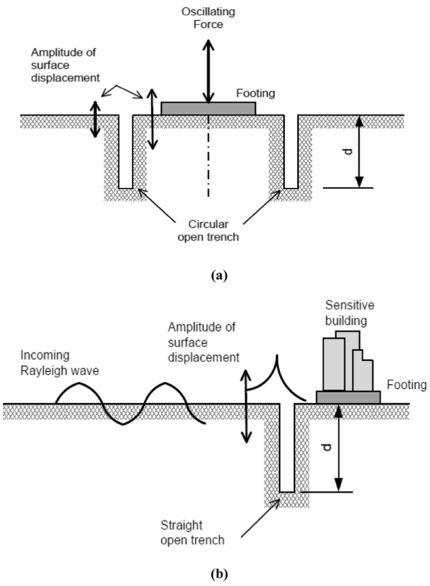
## 6. FAB Building & Cleanroom Architecture

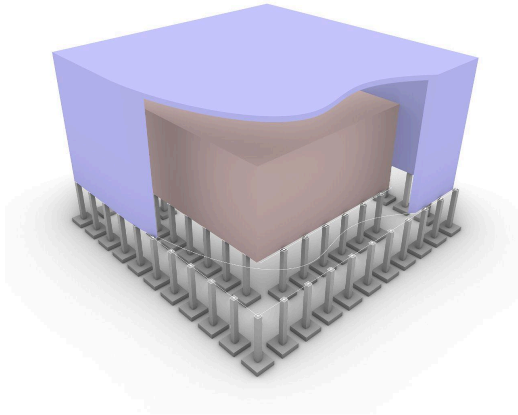
### 6.1. Structural System for Vibration Isolation

Vibration isolation is the most critical consideration in the structural design of semiconductor FABs. To mitigate vibrations, the structural system isolates the cleanroom on all five sides that meet the ground. The typical configuration includes an interior building housing the cleanroom, protected by an exterior shell building. These two buildings are structurally independent, with no physical contact to prevent lateral vibration transfer through the ground. Their foundations are separated by a trench, with additional deep trenches often constructed around the exterior building for enhanced isolation.

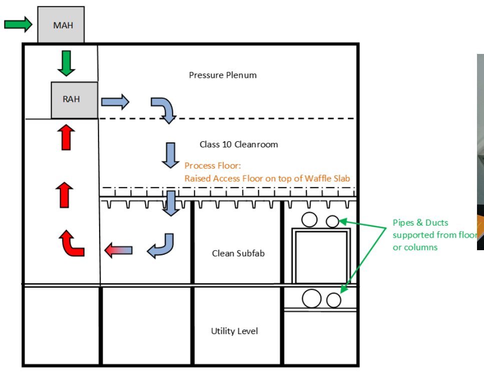
To counter vibrations originating deep within the earth, the concrete slab supporting the interior building is typically over a meter thick, using its mass to dampen vibrations. Vibration-absorbing rubber sheets are embedded within the slab to further reduce upward vibration transmission. Wherever connections are necessary between the two buildings or across the trenches, rubber strips are installed along corridor edges and panel joints to absorb and minimize vibration transfer.

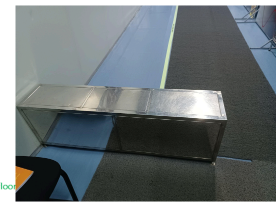
Within the cleanroom, stilted floor tiles and slits over the sub-fab are equipped with shock-absorbing springs and are isolated from one another. This design ensures that vibrations originating from machinery in one part of the room do not spread across the floor surface to other machines, maintaining stability and precision throughout the cleanroom environment.



### 6.2. Floor Layouts and Sections



## 7. Human Experience of FABs

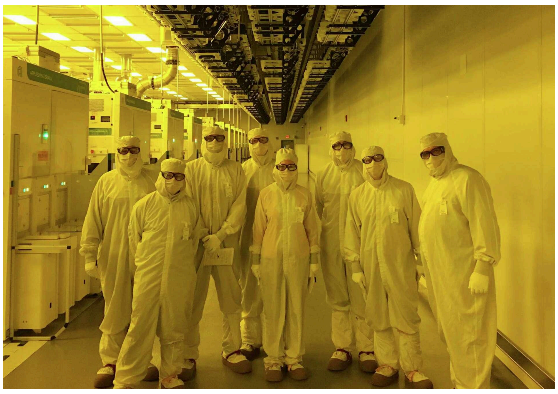
### 7.1. Demands and Challenges

Working in a semiconductor fabrication facility (FAB) is a unique experience, demanding both precision and adaptability from its workforce. Employees often come from technical and engineering backgrounds, including degrees in engineering, physics, or materials science, while technicians typically have vocational training. The skill level required is high, as the work involves operating advanced machinery and maintaining strict protocols. While automated systems handle most production tasks, human expertise is essential for monitoring, troubleshooting, and ensuring smooth operations.

The physical environment within a FAB is unlike any other workplace. The cleanroom's highly controlled conditions demand strict adherence to rules. Employees must remove all jewelry, avoid makeup, and only use approved tools and materials to prevent contamination. Even scratching your face is regulated to avoid shedding particles. Workers wear full-body "bunny suits" with hoods and face masks to protect the cleanroom environment from human contaminants. While the suits are not particularly uncomfortable, the face masks can feel restrictive over long shifts.

Inside the FAB, employees navigate raised metal floors that enhance airflow and reduce particle accumulation. The constant hum of HEPA filters creates a noisy atmosphere, and the lighting varies between sterile industrial white and yellow in areas with photosensitive chemicals. The yellow lighting, while essential for processes like lithography, can cause headaches for some workers, who may need blue-tinted safety glasses to mitigate the effects.

Work in the FAB is largely automated, with robots handling wafer transportation and positioning. Humans monitor instrument readouts, inspect processes, and maintain equipment. The rules are strict and meticulous, extending even to the direction tools must be cleaned or scrubbed. These stringent protocols reflect the precision required in semiconductor manufacturing, where even minor contamination can disrupt production for weeks.



### 7.2. Health Concerns

Although the cleanroom environment minimizes exposure to traditional industrial hazards, it can pose unique challenges. The cool temperature (around 20°C) and low humidity may reduce sweating, which is essential for removing excess salts from the body. Over time, this could lead to imbalances if not mitigated with physical activity during breaks. Limited mobility and repetitive tasks could result in muscle stiffness or reduced circulation for some individuals. The constant noise from HEPA filters and the lighting variations might cause occasional discomfort, such as headaches or mental fatigue.

Psychologically, the isolation and monotony of the cleanroom environment can be challenging for some. The restrictive rules and long shifts may create a sense of detachment for workers unaccustomed to such conditions. However, most employees adapt well, and proactive measures, such as incorporating physical activity and mental health support, can address these challenges.

### 7.3. Solutions for Worker Well-Being

Architectural and site design play a crucial role in supporting employee well-being. Break areas with biophilic elements, such as landscaped gardens or indoor greenery, can provide a refreshing change of pace. Recreational spaces, like fitness centers or walking tracks, encourage physical activity to counteract the lack of sweating and mobility during shifts. Well-lit breakrooms with natural light can help alleviate mental fatigue and restore circadian balance.

The inclusion of landscaped outdoor spaces near break areas allows employees to spend time in natural surroundings during their shifts. Such spaces can serve as retreats, enabling workers to recharge physically and mentally before returning to the demanding cleanroom environment.

### 7.4. Positive Experiences and Rewards

Despite the challenges, many employees describe working in a FAB as an exhilarating experience. Being surrounded by cutting-edge technology and automated systems feels like stepping into a science fiction movie. Robots, though not humanoid, dominate the cleanroom, gracefully moving wafers with mechanical precision. For many, the opportunity to work in such a futuristic environment is a source of pride and excitement.

Employees often take great satisfaction in knowing their work contributes to advancements in modern technology. The knowledge that they play a role in creating products that power smartphones, electric vehicles, and space exploration fosters a deep sense of accomplishment. This connection to the end product, combined with recognition from family, friends, and the broader community, enhances job satisfaction.

### 7.5. Community Engagement & Education

FAB facilities could foster stronger community connections through outreach programs, educational initiatives, and visitor-friendly spaces. Training centers or exhibition areas within the facility could showcase the processes and innovations of semiconductor manufacturing, inspiring schoolchildren and college students to explore careers in this field. Interactive displays, guided tours, and public events could demystify the industry, building awareness of its critical role in modern life.

## 8. Conclusions

This research paper is designed to guide architects and other professionals in understanding the unique architectural requirements of semiconductor FABs. It explains the fundamental principles of the semiconductor electronics industry and the critical design elements necessary to create functional, efficient, and innovative FABs. By addressing essential aspects like contamination control, vibration isolation, EMI shielding, and utility integration, the paper provides a foundational overview for designing these highly specialized facilities.

In addition to functional and technical requirements, the research highlights the importance of considering human well-being and aesthetics in FAB design. It explores the challenges faced by cleanroom engineers, such as working long hours in restrictive suits, limited mobility, and the psychological strain of highly controlled artificial environments. The paper advocates for integrating thoughtful design solutions such as recreational spaces within the facility, natural landscaping, opportunities for community and educational engagement, and fostering a connection with the end product. It emphasizes creating an environment where workers can feel pride in their contributions to a vital industry, enhancing both their well-being and their sense of accomplishment.

These principles are directly connected to my thesis, "Semiconductor Electronics Technology Park: An Iconic Hub for Chip Design, Manufacturing, R&D, and Educational Engagement." My thesis aims to create a facility that not only addresses the technical demands of semiconductor manufacturing but also prioritizes the human experience and incorporates an architectural language that reflects the industry's national and global importance. Through this work, I hope to contribute to setting new standards in the design of industrial and research spaces.

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